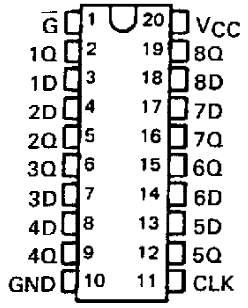
SN54LS377, SN54LS378, SN54LS379, SN74LS377, SN74LS378, SN74LS379
OCTAL, HEX, AND QUAD D-TYPE FLIP-FLOPS WITH ENABLE

SDLS167

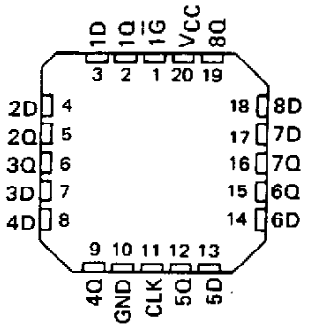
OCTOBER 1976 – REVISED MARCH 1988

- 'LS377 and 'LS378 Contain Eight and Six Flip-Flops, Respectively, with Single-Rail Outputs
- 'LS379 Contains Four Flip-Flops with Double-Rail Outputs
- Individual Data Input to Each Flip-Flop
- Applications Include:
  - Buffer/Storage Registers
  - Shift Registers
  - Pattern Generators

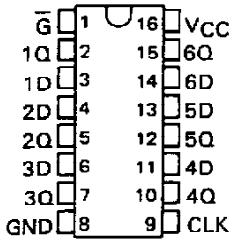
SN54LS377 . . . J PACKAGE
SN74LS377 . . . DW OR N PACKAGE
(TOP VIEW)



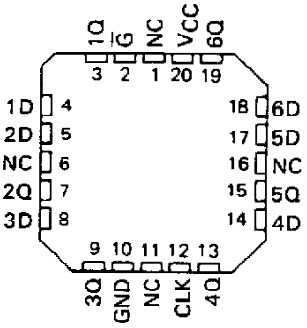
SN64LS377 . . . FK PACKAGE
(TOP VIEW)



SN54LS378 . . . J OR W PACKAGE
SN74LS378 . . . D OR N PACKAGE
(TOP VIEW)



SN54LS378 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These monolithic, positive-edge-triggered flip-flops utilize TTL circuitry to implement D-type flip-flop logic with an enable input. The 'LS377, 'LS378, and 'LS379 devices are similar to 'LS273, 'LS174, and 'LS175, respectively, but feature a common enable instead of a common clear.

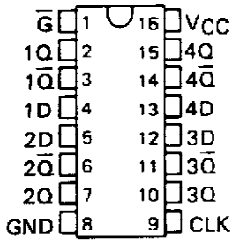
Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if the enable input $\overline{G}$ is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at the $\overline{G}$ input.

These flip-flops are guaranteed to respond to clock frequencies ranging from 0 to 30 MHz while maximum clock frequency is typically 40 megahertz. Typical power dissipation is 10 milliwatts per flip-flop.

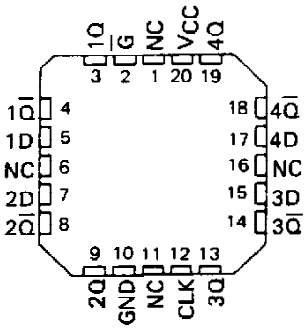
FUNCTION TABLE
(EACH FLIP-FLOP)

INPUTS			OUTPUTS	
$\overline{G}$	CLOCK	DATA	Q	$\overline{Q}$
H	X	X	Q_0	$\overline{Q}_0$
L	↑	H	H	L
L	↑	L	L	H
X	L	X	Q_0	$\overline{Q}_0$

SN54LS379 . . . J OR W PACKAGE
SN74LS379 . . . D OR N PACKAGE
(TOP VIEW)

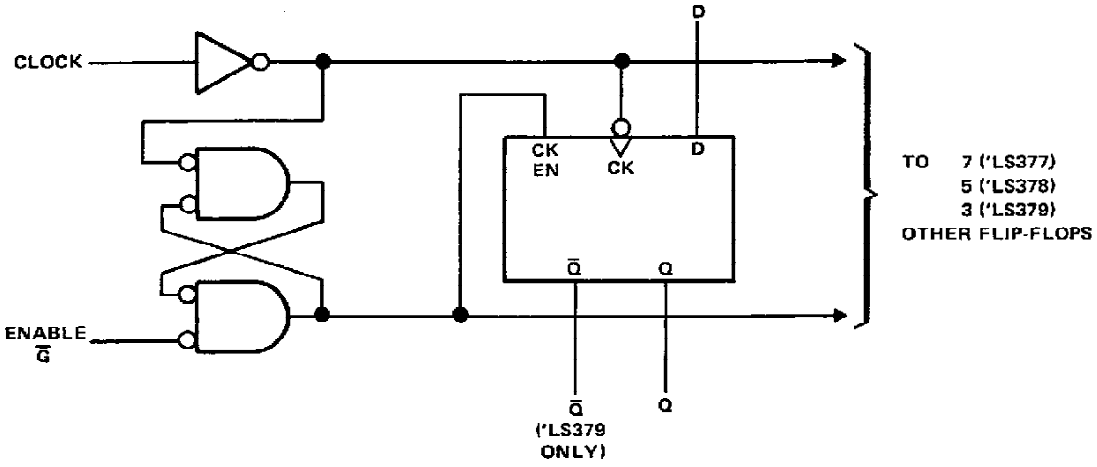


SN54LS379 . . . FK PACKAGE
(TOP VIEW)



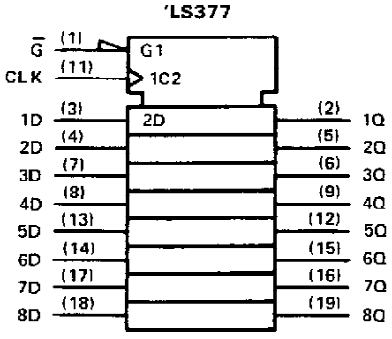
NC – No internal connection

logic diagram (positive logic)

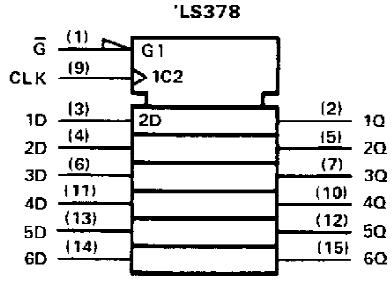


logic symbols†

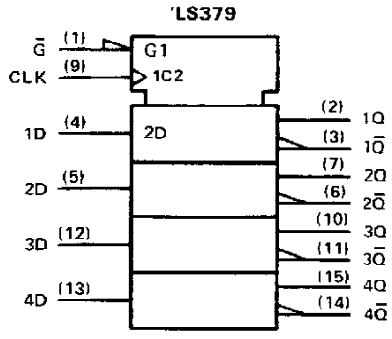
'LS377



'LS378



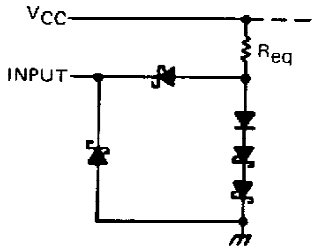
'LS379



† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for DW, J, and N packages.

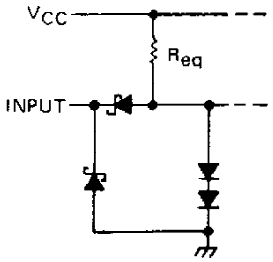
schematics of inputs and outputs

EQUIVALENT OF DATA INPUT



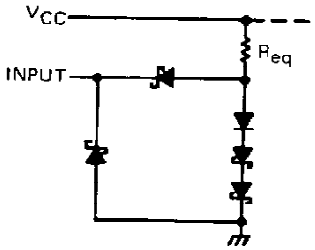
'LS379 : R_{eq} = 30 kΩ NOM
others : R_{eq} = 25 kΩ NOM

EQUIVALENT OF CLOCK INPUTS



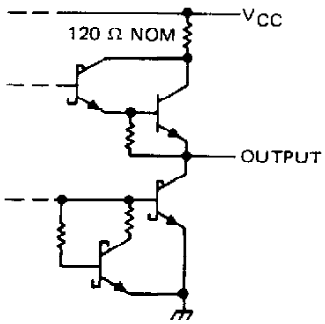
'LS379 :R_{eq} = 17 kΩ NOM
others :R_{eq} = 20 kΩ NOM

EQUIVALENT OF ENABLE INPUTS



'LS379 :R_{eq} = 25 kΩ NOM
others :R_{eq} = 20 kΩ NOM

TYPICAL OF ALL OUTPUTS



absolute maximum rating over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS' . . . . . −55°C to 125°C
SN74LS' . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS'			SN74LS'			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}				−400			−400	μA
Low-level output current, I_{OL}				4			8	mA
Clock frequency, f_{clock}		0		30	0		30	MHz
Width of clock pulse, t_w		20			20			ns
Setup time, t_{su}	Data input	20↑			20↑			ns
	Enable active-state	25↑			25↑			
	Enable inactive-state	10↑			10↑			
Hold time, t_h	Data and enable	5↑			5↑			ns
Operating free-air temperature, T_A		−55		125	0		70	°C

↑ The arrow indicates that the rising edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†			SN54LS'			SN74LS'			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.7			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −18 mA				−1.5			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IL} = V_{IL} max,	V_{IH} = 2 V, I_{OH} = −400 μA		2.5	3.5		2.7	3.5		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IL} = V_{IL} max	V_{IH} = 2 V,	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
				I_{OL} = 8 mA					0.35	0.5	
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 7 V				0.1			0.1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V				20			20	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V				−0.4			−0.4	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX			−20		−100	−20		−100	mA
I_{CC}	Supply current	V_{CC} = MAX,	See Note 2	'LS377		17	28		17	28	mA
				'LS378		13	22		13	22	mA
				'LS379		9	15		9	15	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Note more than one input should be shorted at a time, and duration of the short-circuit should not exceed one second.
NOTE 2: With all outputs open and ground applied to all data and enable inputs, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to clock.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency	C_L = 15 pF, R_L = 2 kΩ, See Note 3	30	40		MHz
t_{PLH}	Propagation delay time, low-to-high-level output from clock			17	27	ns
t_{PHL}	Propagation delay time, high-to-low-level output from clock			18	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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